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PMP10214 REV B Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB1	1		PMP10214	Any	Printed Circuit Board	
2	C1, C101, C108	3	220uF	EEE-FK1H221P	Panasonic	CAP, AL, 220 μF, 50 V, +/- 20%, 0.18 ohm, SMD	SMT Radial G
3	C2, C3, C4, C5, C102, C103, C104, C105	8	10uF	GRM32ER71H106KA12L	MuRata	CAP, CERM, 10 μF, 50 V, +/- 10%, X7R, 1210	1210
4	C6, C7, C8, C9, C10, C11, C106, C107	8	22uF	GRM32ER71E226KE15L	MuRata	CAP, CERM, 22 μF, 25 V, +/- 10%, X7R, 1210	1210
5	C12	1	1uF	GRM219R71E105KA88D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0805	0805
6	C13, C14, C111	3	330uF	25SVPF330M	Panasonic	CAP, Polymer, 330 μF, 25 V, +/- 20%, 0.014 ohm, F12, SMD, 2-Leads, Body 10.5x10.5mm, Height 12.7mm SMD	F12, SMD, 2-Leads, Body 10.5x10.5mm, Height 12.7mm
7	C15, C23, C26	3	47pF	GRM1885C1H470JA01D	MuRata	CAP, CERM, 47pF, 50V, +/-5%, C0G/NP0, 0603	0603L
8	C16		4.7uF	GRM21BR71C475KA73L	MuRata	CAP, CERM, 4.7 µF, 16 V, +/- 10%, X7R, 0805	0805
9	C17, C25	2	1uF	GRM188R61H105KAALD	MuRata	CAP, CERM, 1 µF, 50 V, +/- 10%, X5R, 0603	0603
10	C18, C19	2	0.22uF	GRM188R71E224KA88D	MuRata	CAP, CERM, 0.22 µF, 25 V, +/- 10%, X7R, 0603	0603
11	C20, C30	2	100pF	GRM1885C2A101JA01D	MuRata	CAP, CERM, 100pF, 100V, +/-5%, C0G/NP0, 0603	0603L
12	C21	1	0.47uF	GRM188R71C474KA88D	MuRata	CAP, CERM, 0.47 µF, 16 V, +/- 10%, X7R, 0603	0603
13	C22	1	0.056uF	GRM188R71H563KA93D	MuRata	CAP, CERM, 0.056 µF, 50 V, +/- 10%, X7R, 0603	0603
14	C24	1	0.33uF	GRM188R71C334KA01D	MuRata	CAP, CERM, 0.33 µF, 16 V, +/- 10%, X7R, 0603	0603
15	C27	1	0.022uF	C0603C223K5RACTU	Kemet	CAP, CERM, 0.022uF, 50V, +/-10%, X7R, 0603	0603
16	C28	1	470pF	GRM188R71H471KA01D	MuRata	CAP, CERM, 470 pF, 50 V, +/- 10%, X7R, 0603	0603
17	C29	1	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
18	C109, C110, C112	3	0.1uF	GRM188R72A104KA35D	MuRata	CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0603	0603
19	D1	1	30V	B530C-13-F	Diodes Inc.	Diode, Schottky, 30 V, 5 A, SMC	SMC
20	D2	1	60V	B560C-13-F	Diodes Inc.	Diode, Schottky, 60 V, 5 A, SMC	SMC
21	D3	1	60V	PMEG6010CEJ,115	NXP Semiconductor	Diode, Schottky, 60 V, 1 A, SOD-323F	SOD-323F
22	D4, D5	2	100V	BAS316,115	NXP Semiconductor	Diode, Ultrafast, 100V, 0.25A, SOD-323	SOD-323
23	H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
24	H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
25	J1, J2	2		PEC03SAAN	Sullins Connector Solutions	Header, 100mil, 3x1, Tin, TH	Header, 3 PIN, 100mil, Tin
26	J3	1		PEC02SAAN	Sullins Connector Solutions	Header, 100mil, 2x1, Tin, TH	Header, 2 PIN, 100mil, Tin
27	L1	1	2.2uH	IHLP8787MZER2R2M5A	Vishay-Dale	Inductor, Shielded, 2.2 µH, 48 A, 0.00123 ohm, SMD	22x22.48mm
28	L101	1	100nH	SLC1049-101MLB	Coilcraft	Inductor, Shielded, Ferrite, 100 nH, 43 A, 0.000273 ohm, SMD	10.2x5.16x6.88mm
29	Q1, Q2	2	40V	BSC010N04LS	Infineon Technologies	MOSFET, N-CH, 40 V, 100 A, PG-TDSON-8	PG-TDSON-8
30	Q3, Q4		40V	BSC010N04LSI	Infineon Technologies	MOSFET, N-CH, 40 V, 100 A, PG-TDSON-8	PG-TDSON-8
31	Q5, Q6	2	25V	BSC009NE2LS5I	Infineon Technologies	MOSFET, N-CH, 25 V, 100 A, PG-TDSON-8	PG-TDSON-8
32	Q7, Q8	2	25V	BSC009NE2LS5	Infineon Technologies	MOSFET, N-CH, 25 V, 100 A, PG-TDSON-8	PG-TDSON-8

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
33	R1, R101	2	0.005	FCSL64R005FER	Ohmite	RES, 0.005, 1%, 2 W, 2512 WIDE	2512 WIDE
34	R2, R3, R4, R5, R12, R15, R17, R24, R25, R26, R27	11	0	RC0603JR-070RL	Yageo America	RES, 0 ohm, 5%, 0.1W, 0603	0603L
35	R6, R8, R16, R21	4	100	RC0603FR-07100RL	Yageo America	RES, 100 ohm, 1%, 0.1W, 0603	0603L
36	R7	1	0.002	KRL11050-C-R002-G-T1	Susumu Co Ltd	RES, 0.002, 2%, 6 W, 4320_WIDE	4320_WIDE
37	R9	1	10.0	RC0603FR-0710RL	Yageo America	RES, 10.0 ohm, 1%, 0.1W, 0603	0603L
38	R10	1	10.0k	RC0603FR-0710KL	Yageo America	RES, 10.0k ohm, 1%, 0.1W, 0603	0603L
39	R11	1	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9, 1%, 0.1 W, 0603	0603
40	R13	1	499k	CRCW0603499KFKEA	Vishay-Dale	RES, 499 k, 1%, 0.1 W, 0603	0603
41	R14		100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
42	R18	1	64.9k	CRCW060364K9FKEA	Vishay-Dale	RES, 64.9 k, 1%, 0.1 W, 0603	0603
43	R19	1	93.1k	RC0603FR-0793K1L	Yageo America	RES, 93.1 k, 1%, 0.1 W, 0603	0603
44	R20		118k	CRCW0603118KFKEA	Vishay-Dale	RES, 118 k, 1%, 0.1 W, 0603	0603
45	R22	1	4.99k	CRCW06034K99FKEA	Vishay-Dale	RES, 4.99 k, 1%, 0.1 W, 0603	0603
46	R23	1	6.81k	CRCW06036K81FKEA	Vishay-Dale	RES, 6.81 k, 1%, 0.1 W, 0603	0603
47	T1, T2, T3, T4	4	50A	CB35-36-CY	Panduit	Terminal 50A Lug	CB35-36-CY
48	TP1, TP3		Red	5005	Keystone	Test Point, Compact, Red, TH	Red Compact Testpoint
49	TP2, TP4	2	Black	5006	Keystone	Test Point, Compact, Black, TH	Black Compact Testpoint
50	TP5	1	PGOOD	5007	Keystone	Test Point, Compact, White, TH	White Compact Testpoint
51	TP6, TP105, TP107	3	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
52	TP7	1	White	5007	Keystone	Test Point, Compact, White, TH	White Compact Testpoint
53	TP101, TP102	2	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
54	TP103	1	Orange	5003	Keystone	Test Point, Miniature, Orange, TH	Orange Miniature Testpoint
55	TP104, TP106	2	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
56	U1	1		LM5175PWPR	Texas Instruments	42V Wide VIN 4-Switch Synchronous Buck-Boost Controller, PWP0028F	PWP0028F

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